LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSIOMER:				
MODULE NO.:	WO12864H-TMI#			
APPROVED BY:				
(FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:		

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
J	2020/12/23		Add Interface



MODLE NO:

華凌光電股份有限公司

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2012/01/31		First issue
A	2013/05/27		Modify B/L information
В	2013/10/31		Add Pull Tape
C	2014/07/17		Modify pull tape.
D	2016/01/27		Modify Precautions in use
			of LCD Modules
			& Static electricity test
Е	2016/04/21		Modify Response Time
F	2016/05/18		Modify Contour Drawing.
G	2016/11/21		Add FPC bending rule
Н	2019/08/27		Modify Material List of
			Components for RoHs
I	2019/12/17		Modify Precautions in use
			of LCD Modules
$\overline{\mathbf{J}}$	2020/12/23		Add Interface

Contents

- 1. Module Classification Information
- 2.Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage

1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 128 * 64 dot

Model serials no.

 \bigcirc Backlight Type: N \rightarrow Without backlight T \rightarrow LED, White L \rightarrow LED, Full color

 $B\rightarrow EL$, Blue green $A\rightarrow LED$, Amber $J\rightarrow DIP$ LED, Blue $D\rightarrow EL$, Green $R\rightarrow LED$, Red $K\rightarrow DIP$ LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M \rightarrow EL$, Yellow Green $G \rightarrow LED$, Green $H \rightarrow DIP$ LED, Amber $F \rightarrow CCFL$, White $P \rightarrow LED$, Blue $I \rightarrow DIP$ LED, Red

 $Y \rightarrow LED$, Yellow Green $X \rightarrow LED$, Dual color $G \rightarrow LED$, Green $C \rightarrow LED$, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

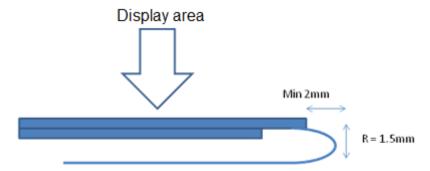
Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00 B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00

E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



(12)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

3.General Specification

Item	Dimension	Unit
Number of dots	128 x 64	_
Module dimension	80.0 x 54.0 x 9.5	mm
View area	70.7 x 38.8	mm
Active area	66.52 x 33.24	mm
Dot size	0.48 x 0.48	mm
Dot pitch	0.52 x 0.52	mm
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color can only guarantee the same color in the same be	
Duty	1/65 , 1/9 Bias	
View direction	6 o'clock	
Backlight Type	LED, White	
IC	ST7567-G	
Interface	6800/8080/4-Line SPI	

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	VI	-0.3	_	V _{DD} +0.3	V
Digital Power Supply Voltage	V _{DD} -V _{SS}	-0.3	_	3.6	V
LCD Power supply voltage	V0-XV0	-0.3	_	16	V

5.Electrical Characteristics

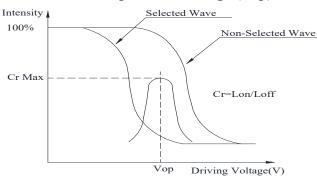
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$ m V_{DD} ext{-}V_{SS}$	_	3.0	3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	XV0-V0	Ta=25°℃	_	10.0	_	V
		Ta=70°C	_	_	_	V
Input High Volt.	$ m V_{IH}$	_	$0.7V_{DD}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	Vss	_	$0.3V_{DD}$	V
Output High Volt.	V_{OH}	_	$0.8~\mathrm{V_{DD}}$	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	Vss	_	$0.2V_{\mathrm{DD}}$	V
Supply Current(No include LED Backlight)	I_{DD}	V _{DD} =3.3V	_	2.0	_	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

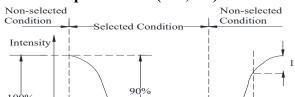
6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
T	θ	CR≧2	0	_	20	$\phi = 180^{\circ}$
	θ	CR≧2	0	_	40	$\phi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	30	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
. Tr'	T rise	_	_	200	300	ms
Response Time	T fall	_	—	250	350	ms

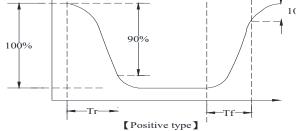
Definition of Operation Voltage (Vop)

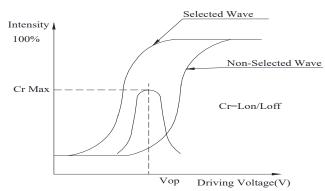


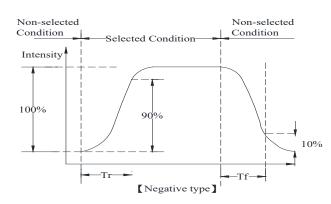




Definition of Response Time (Tr, Tf)







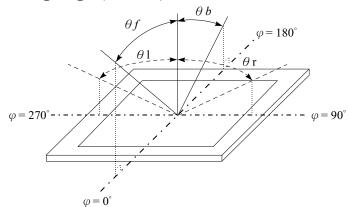
Conditions:

Operating Voltage: Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)



7.Interface Pin Function

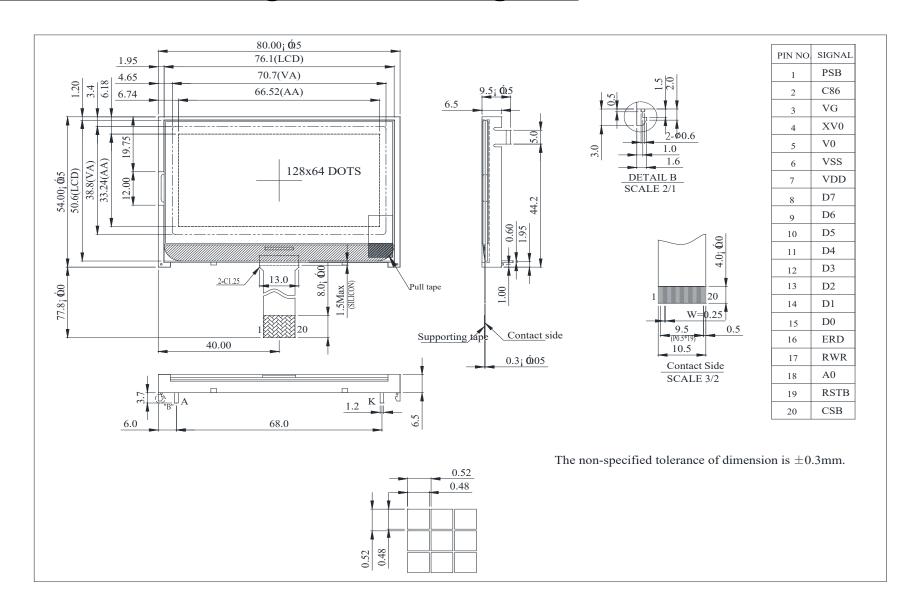
Pin No.	Symbol	Level	Description					
1	PSB	I	PSB se	elects the	interfa	ce type: Serial or Parallel.		
			C86 se	lects the 1	microp	processor type in parallel interface mo	de.	
			PSF	3 C	86	Selected Interface		
			"H'	, "I	Η"	Parallel 6800 Series MPU Interface		
2	C86	I	"H'	' "]	_;,	Parallel 8080 Series MPU Interface		
			"L"	, "]	Χ"	Serial 4-Line SPI Interface		
			Please refer to "APPLICATION NOTES" and "Microprocessor					
			Interface"(Section 6) for detailed connection of the selected interface.					
3	VG	Power	VG is t	the LCD	driving	g voltage for segment circuits.		
4	XV0	Power	XV0 is	the LCD	drivir	ng voltage for common circuits at pos	itive frame.	
5	V0	Power	V0 is tl	he LCD o	lriving	voltage for common circuits at negative	tive frame.	
6	VSS	Power	This is a 0V terminal connected to the system GND.					
7	VDD	Power	Shared with the MPU power supply terminal VDD. (3.3 V)					
		I/O	When using 8-bit parallel interface: (6800 or 8080 mode) 8-bit bi-directional data bus. Connect to the data bus of 8-bit microprocessor. When CSB is non-active (CSB="H"), D[7:0] pins are high impedance.					
8-15	D7-D0	I	When using serial interface: 4-LINE D7=SDA: Serial data input. D6=SCL: Serial clock input. D[5:0] are not used and should connect to "H" by VDD1 or VDDH. When CSB is non-active (CSB="H"), D[7:0] pins are high impedance.					
			Read/V	Vrite exec	cution	control pin. When PSB is "H",		
			C86	MPU Type	ERD	Description		
16	ERD	I	н	6800 series	E	Read/Write control input pin. R/W="H": When E is "H", D[7:0] are in output mode. R/W="L": Signals on D[7:0] are latched at the falling edge of E signal.		
			L	8080 series	/RD	Read enable input pin. When /RD is "L", D[7:0] are in output mode.		
			ERD is not used in serial interface and should fix to "H" by VDD1 or VDDH.					

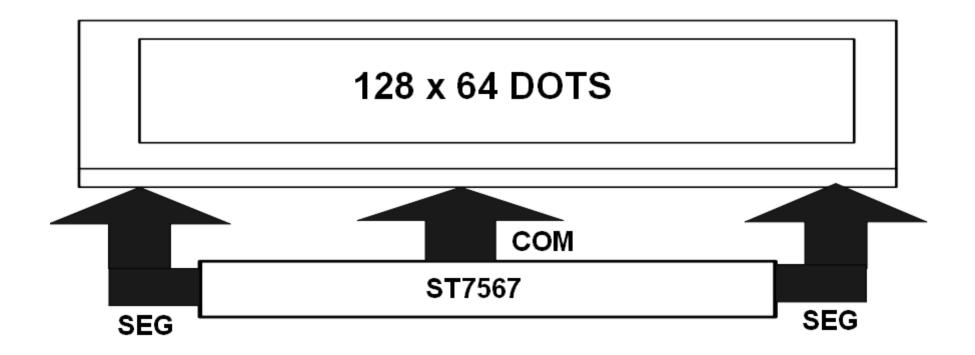
			Read/Write execution control pin. When PSB is "H",					
			C86	MPU Type	RWR	Description		
		н	6800 series	R/W	Read/Write control input pin. R/W="H": read. R/W="L": write.			
17	RWR	I	L	8080 series	WR	Write enable input pin. Signals on D[7:0] will be latched at the rising edge of /WR signal.		
			RWR is not used in serial interface and should fix to "H" by VDD1 or VDDH.					
18	A0	I	It determines whether the access is related to data or command. A0="H": Indicates that signals on D[7:0] are display data. A0="L": Indicates that signals on D[7:0] are command.					
19	RSTB	I	Hardware reset input pin. When RSTB is "L", internal initialization is executed and the internal registers will be initialized.					
20	CSB	I	_	Chip select input pin. Interface access is enabled when CSB is "L". When CSB is non-active (CSB="H"), D[7:0] pins are high impedance.				

C1=C2=1UF/0805

CI=C	2=1UF/(1805
PIN NO.	SIGNAL	
1	PSB	P3.6
2	C86	P3.6
3	VG	
4	XV0	C2 + C1
5	V0	
6	VSS	VSS
7	VDD	VDD
8	D7	P1.7
9	D6	P1.6
10	D5	P1.5
11	D4	P1.4
12	D3	P1.3
13	D2	P1.2
14	D1	P1.1
15	D0	P1.0
16	ERD	P3.4
17	RWR	P3.7
18	A0	P3.0
19	RSTB	P3.2
20	CSB	P3.3

8.Contour Drawing & Block Diagram





9.Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

Environmental Test						
Test Item	Content of Test	Test Condition	Not e			
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2			
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1			
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2			
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles				
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times				

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

10.Backlight Information

Specification

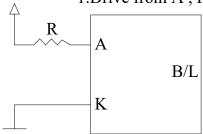
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	96	120	mA	V=3.5V
Supply Voltage	V	3.3	3.5	3.7	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminance (Without LCD)	IV	840	1050	_	CD/M ²	ILED=96mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED=96mA 25°C,50-60%RH, (Note 1)
Color White						

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

LED B\L Drive Method

1.Drive from A, K



11.Inspection specification

NO	Item	Criterion				AQL		
		Missing vertical, horizontal segment, segment contrast defect.						
		Missing character, dot or icon.						
		Display malfunction.						
01	Electrical	No function or no display.						
U1	Testing	Current consumption exceeds product specifications.						
		LCD viewing a	LCD viewing angle defect.					
		Mixed product types.						
		Contrast defect.						
	Black or	2.1 White and b	lack spots	on display ≤ 0.25	mm, no more than			
02	white spots on	three white or b	-		,	2.5		
	LCD (display		-	-	or lines within 3mm			
	only)							
		3.1 Round type						
		$\Phi = (x + y) / 2$		SIZE	Acceptable Q TY			
				$\Phi \leq 0.10$	Accept no dense			
				$0.10 < \Phi \le 0.20$	2			
				$0.20 < \Phi \le 0.25$	1	2.5		
				$0.25 < \Phi$	0			
	LCD black	→X ← ↓ ▼Y						
	spots, white							
03	spots,							
	contamination							
	(non-display)	3.2 Line type : (<u> </u>			
			Length	Width	Acceptable Q TY			
		₩			Accept no dense			
		→ı _L	L≦3.0	$0.02 < W \le 0.03$	2	2.5		
			L≦2.5	$0.03 < W \le 0.05$				
				0.05 < W	As round type			
		If bubbles are v	isible	Size Φ	Acceptable Q TY			
		judge using blace	-	$\Phi \leq 0.20$	Accept no dense			
04	Polarizer	specifications, r	•	$0.20 < \Phi \le 0.50$	3	2.5		
	bubbles	to find, must ch	•	$0.50 < \Phi \le 1.00$	2	2.5		
		specify direction.		1.00<Φ	0			
				Total Q TY				

NO	Item	Criterion						
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination						
		Symbols Define:						
		x: Chip length	y: Chip width z: C	hip thickness				
		k: Seal width	t: Glass thickness a: L	CD side length				
		L: Electrode pad length:						
		6.1 General glass chip						
		6.1.1 Chip on panel su	rface and crack between	n panels:				
		z: Chip thickness	y: Chip width	x: Chip length				
		Z≦1/2t	Not over viewing	x ≤ 1/8a				
06	Chipped		area		2.5			
	glass	$1/2t < z \le 2t$	Not exceed 1/3k	$x \leq 1/8a$				
		6.1.2 Corner crack:	re chips, x is total length	i of each emp.				
		z: Chip thickness	y: Chip width	x: Chip length				
		Z ≤ 1/2t	Not over viewing area	x≤1/8a				
		$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a				
		⊙ If there are 2 or more chips, x is the total length of each chip.						

NO	Item	Criterion			AQL				
			•	thickness side length					
		y: Chip width x: Ch	ip length z	:: Chip thickness					
		$y \le 0.5 \text{mm}$ $x \le 1/2$	8a ($0 < z \le t$					
		6.2.2 Non-conductive portion:							
06	Glass crack	y X		T Z	2.5				
		y: Chip width x:	Chip length	z: Chip thickness					
			≤ 1/8a	$0 < z \le t$					
		 ⊙ If the chipped area touches to remain and be inspected accorded. ⊙ If the product will be heat seen be damaged. 6.2.3 Substrate protuberance and years. 	he ITO terminal, or ling to electrode ter ealed by the custom	ver 2/3 of the ITO must rminal specifications.					

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
Backlight elements		8.1 Illumination source flickers when lit.8.2 Spots or scratched that appear when lit must be judged.Using LCD spot, lines and contamination standards.	0.65 2.5
		8.3 Backlight doesn't light or color wrong.	0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.	2.5
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	2.5
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB · COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
		10.9 The Scraping testing standard for Copper Coating of PCB X X * Y <= 2mm ²	2.5
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited 100 1000 1000 1000 1000 1000 1000 100								1000		
Value ppm ppm ppm ppm ppm ppm ppm ppm ppm pp									ppm	
Above limited value is set up according to RoHS.										

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

le Number :		Page:
Panel Specification:	□ n	
Panel Type:	☐ Pass	□ NG ,
. View Direction:	☐ Pass	□ NG ,
Numbers of Dots:	☐ Pass	NG,
. View Area:	☐ Pass	□ NG ,
6. Active Area:	☐ Pass	□ NG ,
6. Operating Temperature:	☐ Pass	□ NG ,
Storage Temperature :	Pass	☐ NG ,
3. Others:		
Mechanical Specification :		_
. PCB Size:	☐ Pass	□ NG ,
P. Frame Size:	☐ Pass	□ NG ,
. Materal of Frame:	Pass	□ NG ,
. Connector Position:	Pass	□ NG ,
Fix Hole Position:	Pass	□ NG ,
5. Backlight Position:	☐ Pass	□ NG ,
. Thickness of PCB:	Pass	□ NG ,
B. Height of Frame to PCB:	Pass	□ NG ,
Height of Module:	Pass	□ NG ,
0. Others:	Pass	□ NG ,
Relative Hole Size:		
. Pitch of Connector:	Pass	□ NG ,
. Hole size of Connector:	Pass	□ NG ,
. Mounting Hole size:	Pass	□ NG ,
. Mounting Hole Type:	☐ Pass	□ NG ,
. Others:	☐ Pass	□ NG ,
Backlight Specification:		
. B/L Type:	Pass	□ NG ,
. B/L Color:	☐ Pass	□ NG ,
B/L Driving Voltage (Refere	ence for LED	
. B/L Driving Current:	Pass	□ NG ,
5. Brightness of B/L:	Pass	□ NG ,
B/L Solder Method:	Pass	□ NG ,
. Others:	Pass	□ NG ,



odu	le Number:		Page: 2			
5、	Electronic Characteristics of	f Module:				
1.	Input Voltage:	Pass	□ NG ,			
2.	Supply Current:	Pass	□ NG ,			
3.	Driving Voltage for LCD:	☐ Pass	□ NG ,			
4.	Contrast for LCD:	☐ Pass	□ NG ,			
5.	B/L Driving Method:	Pass	□ NG ,			
6.	Negative Voltage Output:	Pass	□ NG ,			
7.	Interface Function:	Pass	□ NG ,			
8.	LCD Uniformity:	Pass	□ NG ,			
9.	ESD test:	Pass	□ NG ,			
10.	Others:	Pass	□ NG ,			
5 、	Summary :					
	Sales signature:					
	Customer Signature:		Date : / /			